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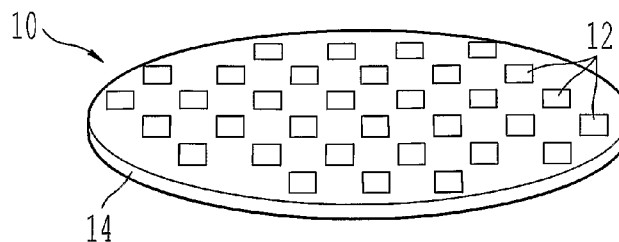
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(54) Title: WAFER SCALE DIE HANDLING



(57) Abstract: A waffle pack device including a member having recesses in a surface of the member to accommodate die from at least one semiconductor wafer. The member is compatible with semiconductor wafer handling equipment and/or semiconductor wafer processing. Preferably, the member accommodates at least a majority of die from a semiconductor wafer. Further, one semiconductor device assembly method is provided which removes die from a singular waffle pack device, places die from the single waffle pack device on a semiconductor package to assemble from the placed die all die components required for an integrated circuit, and electrically interconnects the placed die in the semiconductor package to form the integrated circuit. Another semiconductor device assembly method is provided which removes die from at least one waffle pack device, places die from the at least one waffle pack device on a semiconductor package to assemble from the placed die device components required for an integrated circuit, and electrically interconnects the placed die in the semiconductor package to form the integrated circuit.



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